PCB Integration Mounting Pillars

Specifications

- Inner Raw Material: Ms58 (C3602) Copper alloy
- First Plating Layer: Copper Flash
- Second Plating Layer: Nickel plating (1µm)
- Third Plating Layer: Gold plating (0.8µm)
- Colour: Gold
- Stacking Heights: 3mm, 4mm and 5mm
- PCB Mating Board Thickness: 1.6mm
- Weight: 0.35g
- Operating Temperature: -40°C to +100°C

Diagram

Part Number Table

<table>
<thead>
<tr>
<th>Description</th>
<th>Part Number</th>
</tr>
</thead>
<tbody>
<tr>
<td>Pillar For Cinterion Module, 3mm</td>
<td>MPR-14-0076</td>
</tr>
<tr>
<td>Pillar For Cinterion Module, 4mm</td>
<td>MPR-14-0075-F</td>
</tr>
<tr>
<td>Pillar For Cinterion Module, 5mm</td>
<td>MPR-14-0077</td>
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</tbody>
</table>

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